

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	2250310	substrate\$1 or wafer\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/09/16 16:01
2	BRS	L2	3267637	slot or hole or (flow adj path) or passage	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/09/16 16:03
3	BRS	L3	369359	1 and 2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/09/16 16:03
4	BRS	L4	1666429	print\$head or head	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/09/16 16:04
5	BRS	L5	62644	3 and 4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/09/16 16:04
6	BRS	L6	426657	ink	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/09/16 16:04
7	BRS	L7	17196	5 and 6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/09/16 16:05
8	BRS	L8	323678	nozzles or orifices	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/09/16 16:05

	Type	L #	Hits	Search Text	DBs	Time Stamp
9	BRS	L9	8084	7 and 8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/09/16 16:05
10	BRS	L10	44819	remov\$3 with debris	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/09/16 16:06
11	BRS	L11	288	9 and 10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/09/16 16:06